

23. (New) The semiconductor package of claim 19, wherein said plurality of signal transferring means includes a plurality of bonding wires.

24. (New) The semiconductor package of claim 19, wherein said plurality of signal transferring means includes a plurality of conductive adhesive tapes.

25. (New) The semiconductor package of claim 19, wherein said heat-spreading device is metal.

26. (New) The semiconductor package of claim 19, wherein said sealant material has a thermally conductive glue primed thereupon.

REMARKS

The present **Preliminary Amendment** sets forth additional new Claims 19 through 26 directed to a semiconductor device, classified in class 257, subclass 713 and accompanies a **Restriction Response** that cancels non-elected Claims 13 through 18. Applicants respectfully submit that no new matter is added by these claims which are based upon the application as originally filed.

Favorable consideration is respectfully requested.



MARKED-UP CHANGES

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached paper is captioned "**VERSION WITH MARKINGS TO SHOW CHANGES MADE.**"

CONCLUSION

In light of the above amendments and remarks, Applicants respectfully submit that all pending claims as currently presented are in condition for allowance. If, for any reason, the Examiner disagrees, please call the undersigned attorney at 202-624-3947 in an effort to resolve any matter still outstanding *before* issuing another action. The undersigned attorney is confident that any issue which might remain can readily be worked out by telephone.

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Favorable reconsideration is respectfully requested.

Respectfully submitted,

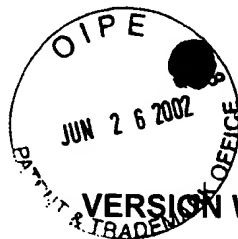
Thomas T. Moga
Registration No. 34,881
Attorney for Applicants

POWELL, GOLDSTEIN, FRAZER & MURPHY, LLP
P.O. Box 97233
Washington, D.C. 20090-7223
202-624-3947

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VERSION WITH MARKINGS TO SHOW CHANGES MADE
(USSN 09/746,018)

IN THE CLAIMS:

The following new Claims 19 through 26 have been added as follows:

19. (New) A semiconductor package, comprising:

a substrate having an underside;

a die positioned on said substrate;

a plurality of signal transferring means electrically connecting said die to
said substrate;

a protective sealant material at least partially formed over said die and
said plurality of signal transferring means, said protective sealant material having
a top;

a heat-spreading device operatively associated with said top of said
protective sealant material; and

a plurality of conductive means attached to said underside of said
substrate.

20. (New) The semiconductor package of claim 19, further including an
adhesive layer between said die and said substrate.

21. (New) The semiconductor package of claim 19 further including a
plurality of printed circuits and external circuits, wherein said plurality of

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conductive means electrically connects said plurality of printed circuits and said external circuits.

22. (New) The semiconductor package of claim 19, wherein said plurality of conductive means includes a plurality of solder balls.

23. (New) The semiconductor package of claim 19, wherein said plurality of signal transferring means includes a plurality of bonding wires.

24. (New) The semiconductor package of claim 19, wherein said plurality of signal transferring means includes a plurality of conductive adhesive tapes.

25. (New) The semiconductor package of claim 19, wherein said heat-spreading device is metal.

26. (New) The semiconductor package of claim 19, wherein said sealant material has a thermally conductive glue primed thereupon.